

Amendments to the Specification:

On page 4, please replace the second full paragraph with the following amended paragraph:

It has been an object of at least one embodiment of the present invention to provide a process for filling trenches in a substrate by depositing a metal layer through ~~electroplating~~.
electroplating.

On page 6, please replace the first full paragraph with the following amended paragraph:

Some examples of accelerators are 3-sulfopropyl disulfide, 41 sulfonated acetylthiourea, 3-mercapto-1-propanesulfonate (MPSA), and ~~dibenzyl-dithio-carbamate~~ dibenzyl-dithio-carbamate.

In the paragraph bridging pages 6 and 7, please replace the paragraph with the following amended paragraph:

For the second plating solution, our preferred accelerator additive has been ~~3-sulfopropyl disulfide~~ 3-sulfopropyl disulfide at a concentration is between about 10 and 50 ppm, but other accelerator additives such as sulfonated acetylthiourea, 3-mercapto-1-propanesulfonate, ~~dibenzyl-dithio-carbamate~~ dibenzyl-dithio-carbamate, 2-mercaptoethanesulfonate, or ~~n, n - dimethyldithiocarbamic acid (3-sulfopropyl)ester~~ n, n - dimethyldithiocarbamic acid (3-sulfopropyl)ester could have also been used. Additionally, the second plating solution will include a long chain polymer (more than about 1,000 units per chain) having high molecular weight (more than about 50,000).

On page 8, please replace the first full paragraph with the following amended paragraph:

Then, in a bath that contains the first plating solution, electroplating onto the wafer surface is initiated and allowed to proceed until sufficient copper has been deposited to overfill all trenches whose width is less than about 0.2 microns while under-filling all trenches whose width exceeds this. At this point, the thickness of deposited copper would typically be between about 0.1 and 0.2 microns. The result is illustrated in FIG. 3 where it can be seen that the narrow trenches 12 have been uniformly over-filled with copper 34 while wide trench 13 is ~~till~~ only partially filled. It is clear that if electroplating were allowed to continue under these conditions, the result would be as was seen in FIG. 1.